AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-7 (canceled).

Claim 8 (currently amended): A process for producing a component-embedded substrate, comprising the steps of:

connecting and fixing a first electronic component to a first electrode pattern on a first supporting layer with a conductive bonding material;

press-bonding a second supporting layer including a second electrode pattern onto the electronic component-fixed surface of the first supporting layer with a first prepreg therebetween to perform transfer;

separating the first supporting layer and the second supporting layer from the first prepreg such that the first and second electrode patterns are disposed on a front surface and a back surface of the first prepreg;

curing the first prepreg before or after the step of separating the first supporting layer and the second supporting layer from the first prepreg;

connecting and fixing a second electronic component onto a back surface of the second electrode pattern with a conductive bonding material after the step of curing the first prepreg;

press-bonding a third supporting layer including a third electrode pattern onto a second electronic component-fixed surface with a second prepreg therebetween to perform transfer;

separating the third supporting layer from the second prepreg; and

curing the second prepreg before or after the step of separating the third supporting layer from the second prepreg, wherein the prepregs and the electrode

patterns are sequentially laminated.

Claim 9 (previously presented): The process for producing the component-embedded substrate according to claim 8, further comprising the steps of:

forming a through hole in the first prepreg which extends in a thickness direction of the first prepreg after curing the prepreg; and

forming a conducting path inside the through hole, the conducting path electrically connecting the first and second electrode patterns provided on the front surface and the back surface of the first prepreg.

Claim 10 (previously presented): The process for producing the component-embedded substrate according to claim 8, further comprising the steps of:

forming a through hole in the first prepreg connecting the electrode pattern provided on the front surface or the back surface of the first prepreg with an external electrode of the first electronic component after curing the first prepreg; and

forming the conducting path inside the through hole, the conducting path electrically connecting the electrode pattern with the external electrode of the first or second electronic component.

Claim 11 (previously presented): The process for producing the component-embedded substrate according to claim 8, wherein the step of curing the first prepreg further comprises the substeps of:

performing temporary curing before separating the first and second supporting layers from the first prepreg; and

performing complete curing after separating the first and second supporting layers from the first prepreg.

Claim 12 (previously presented): The process for producing the component-

embedded substrate according to claim 8, wherein the step of curing the second prepreg further comprises the substeps of:

performing temporary curing before separating the third supporting layer from the second prepreg; and

performing complete curing after separating the third supporting layer from the second prepreg.

Claim 13 (withdrawn): The process for producing the component-embedded substrate according to claim 8, further comprising the steps of:

press-bonding a fourth supporting layer having a fourth electrode pattern onto the surface of the first prepreg with a third prepreg therebetween to perform transfer, the surface being opposite the surface bonded to the second prepreg;

separating the fourth supporting layer from the third prepreg; and

curing the third prepreg before or after the step of separating the fourth supporting layer from the third prepreg.

Claims 14-20 (canceled).